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# 2008 Solar Annual Review Meeting

## *Measurements & Characterization (M&C) Capabilities Overview*

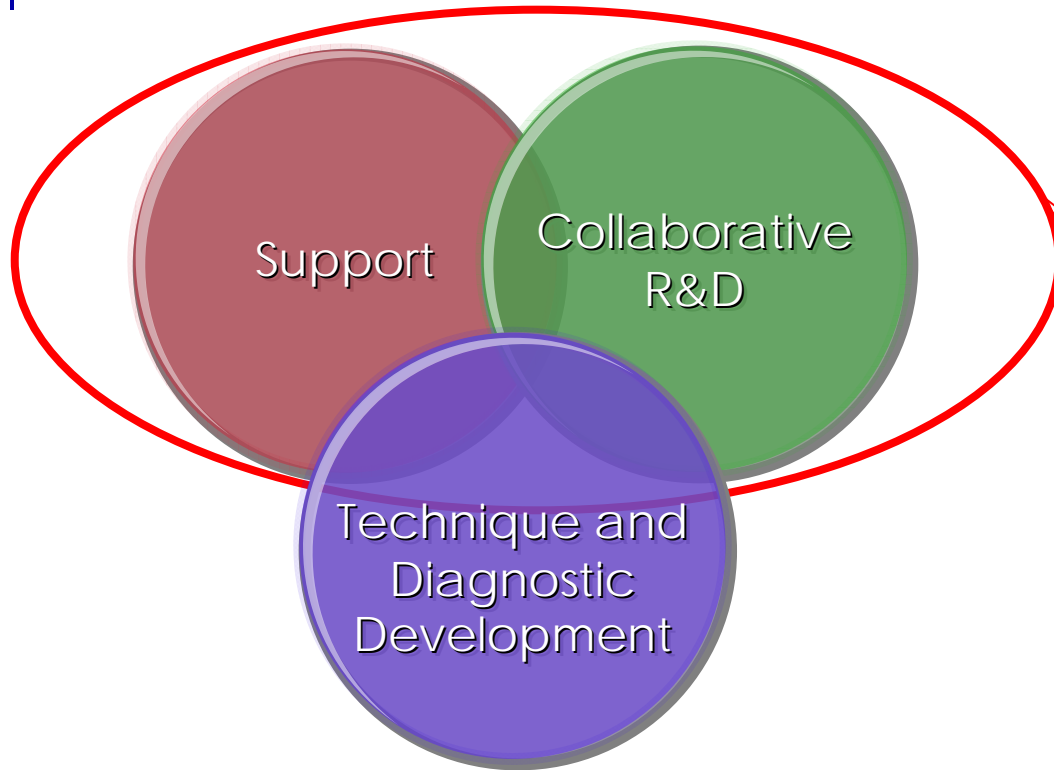


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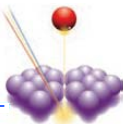


# M&C Mission: Three Focus Areas

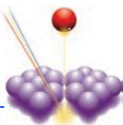
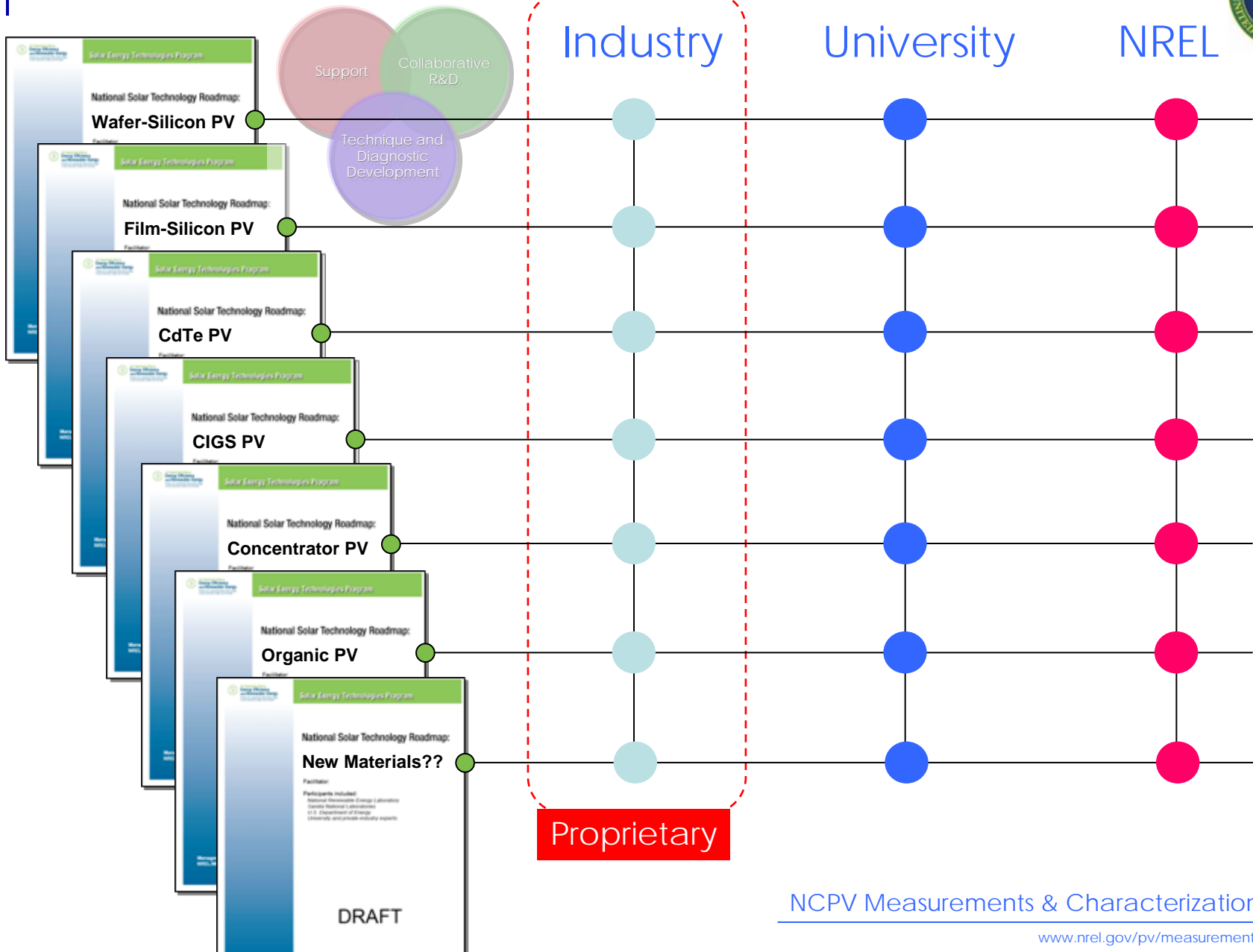


A key component of our mission is to work with SAI subcontractors and help them realize their goals

- Subcontract Stage-gate Review
- Test & Evaluation
- Process Development and Device R&D
- Cell/Module Failure Analysis R&D



# M&C Collaborations

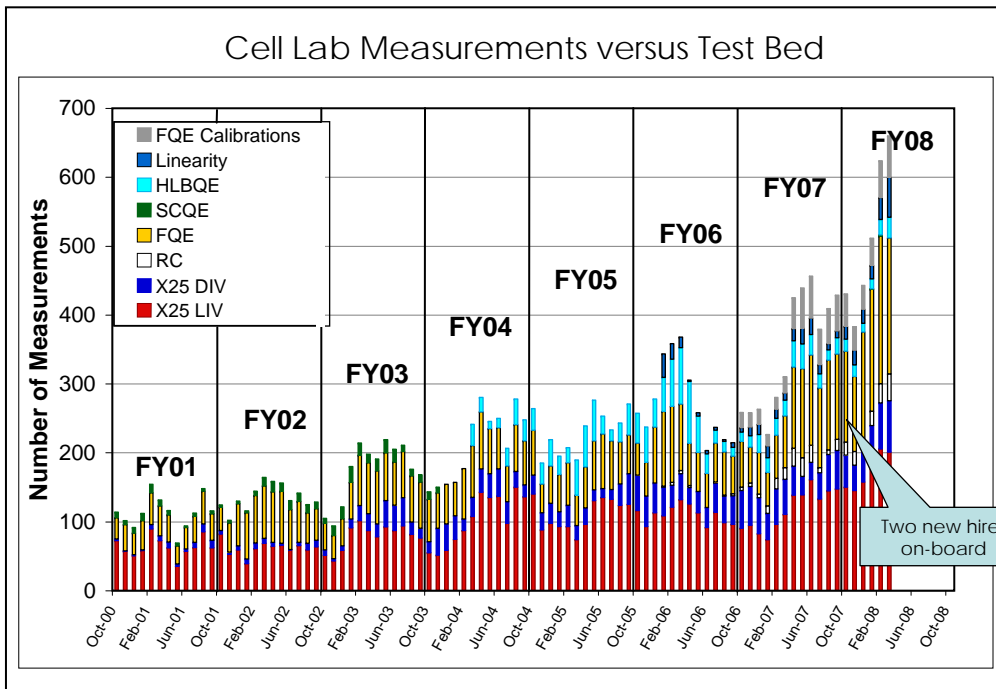


# M&C Supported Subcontracts

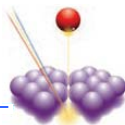


## 2008 Subcontractor Funding:

Photovoltaic Systems R&D Technology Pathway Partnerships (TPPs)	~\$51M
PV Technology Incubator	~18M
University Photovoltaic Product and Process Development	~\$4M
<u>Next Generation Photovoltaic Devices and Processes</u>	<u>~\$7M</u>
<b>TOTAL</b>	<b>~\$80M</b>



- Top priority/preferential treatment for SAI deliverables and stage gate reviews
- Support for all DOE-funded subcontracts on a first come first serve basis (no differentiation between TPP, Incubator, and pre-SAI subcontracts)
- Non-SAI funded PV industry requests



# M&C Core Competency Areas



National Center  
for Photovoltaics (NCPV)

Measurements &  
Characterization

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Device  
Performance

*Keith Emery*  
*keith\_emery@nrel.gov*



Electro-Optical  
Characterization

*Dean Levi*  
*dean\_levi@nrel.gov*



Surface  
Analysis

*Sally Asher*  
*sally\_asher@nrel.gov*



Analytical  
Microscopy

*Mowafak Al-Jassim*  
*mowafak\_aljassim@nrel.gov*

# M&C Core Competency Areas



National Center  
for Photovoltaics (NCPV)

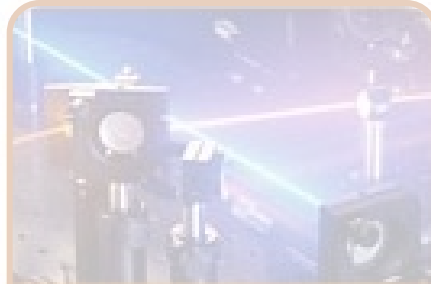
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Electro-Optical  
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Surface  
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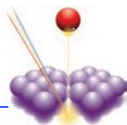
Analytical  
Microscopy

# Cell and Module Performance Team

- *Independent facility for verifying device and module performance for the entire PV community*
- *ISO 17025 accredited for primary reference cell, secondary reference cell and secondary module calibrations*
- *Provide the U.S. PV industry with a calibration traceability path for peak-watt and efficiency measurements to reduce uncertainty in I-V measurements*
  - *Provide reference cell calibrations for the entire US terrestrial community*
- *Develop hardware, software and procedures to accommodate new cell and module technologies. Assists industry in developing measurement system hardware and procedures*



Certificate Number 223601  
ISO 17025 accredited for photovoltaic secondary cell, secondary module and primary reference cell calibration by the American Association for Laboratory Accreditation (A2LA)





# Cell and Module Performance Team Capabilities

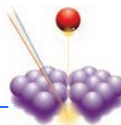


Application	Light Source	Test Bed
<b>1-Sun Cells &amp; Mini-Module</b>		
Spectrolab X25	filtered 3 kW Xe Spectrolab X25 0.1 - 20 suns	30 cm x 30 cm
<b>Concentrator Cells</b>		
Continuous Illumination	1 kW Xenon or 3kW Tungsten 0.1 - 200 suns	1 cm diameter for Xe 5 cm x 10 cm for W
High Intensity Pulsed Solar Simulator (HIPSS)	Xe Flash Lamp 1 to 2000 suns	2 cm x 20 cm
<b>Modules</b>		
Spire 240A Solar Simulator	Xe flash lamp 0.1 to 1.2 suns	61 cm x 122 cm
Spire 4600 Solar Simulator	Pulsed Light Source	137 cm x 200 cm
Spectrolab X200 Large-area Continuous Solar Simulator (LACSS)	Filtered 25 kW Xe 0.1 to 1 suns	122 cm x 152 cm
Standard Outdoor Measurement System (SOMS)	Sunlight	200 cm x 300 cm

*On Order*



- 2,300 gsf of new and reconfigured space
- Required to accommodate large-area solar simulator necessary to support the SAI
- A new Spire 4600 simulator will allow test of modules up to 137 cm x 200 cm (a 265% increase in size)





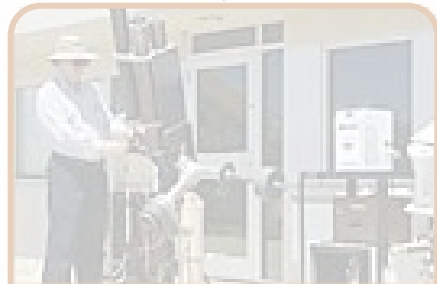
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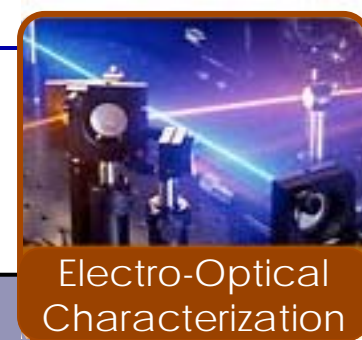


Analytical  
Microscopy

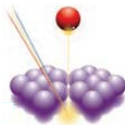
*Dean Levi*  
*dean\_levi@nrel.gov*

# Electro-Optical Characterization Team

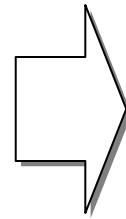
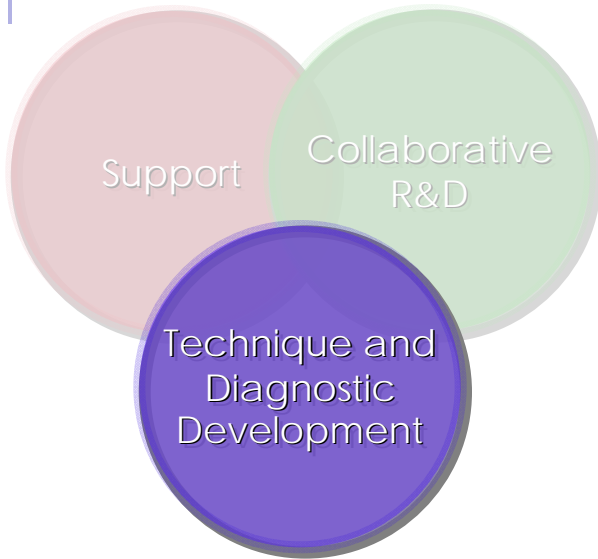
## Capabilities



<b><i>Technique/Capability</i></b>	<b><i>Typical Applications</i></b>
<b><i>Photoluminescence Spectroscopy</i></b>	<i>Measure bandgap and alloy composition; identify defects; provides a quick measure of material quality</i>
<b><i>Minority Carrier Lifetime</i></b> <i>TRPL, RC-PCD, and <math>\mu</math>W-PCD</i>	<i>Measure minority-carrier lifetime, material quality, surface/interface recombination and surface passivation; identify dominant recombination mechanisms</i>
<b><i>Fourier Transform Infrared Spectroscopy</i></b>	<i>Identify chemical composition, chemical bonding; analyze in-situ reactions and concentration of impurities; measure inhomogeneity</i>
<b><i>Spectroscopic Ellipsometry</i></b> <i>VASE and RTSE</i>	<i>Determine optical constants; layer thicknesses; surface/interface roughness; as well as composition crystallinity, alloy composition, and growth dynamics of films</i>
<b><i>Capacitance Techniques</i></b> <i>C-V, DLTS, AS, and DLCP</i>	<i>Measure carrier concentration profiles, interface state densities, and deep-level properties</i>
<b><i>Computational Modeling</i></b>	<i>2-D solar cell modeling and simulation of measurement techniques (TRPL, RC-PCD, EBIC, QE, IV, CL, C-AFM)</i>
<b><i>Diagnostic Development</i></b>	<i>PVSCAN, PV Reflectometer, RC-PCD, PLI, and CDI</i>



# Electro-Optical Diagnostic Development



## *NREL Developed Diagnostics:*

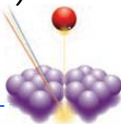
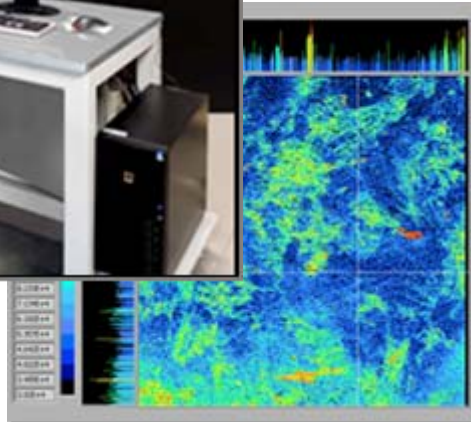
- *PV Scan..... Licensed*
- *PV Reflectometer..... Licensed*
- *RC-PCD..... In-Process*



## GT-PVSCAN 8000



- High-speed optical scanning system designed for characterization of PV materials and cells
  - Technology developed at NREL and licensed to GT Solar
  - 8' x 8" sample size
  - Measurement Modes:
    - Dislocation density
    - Reflectance
    - Light Beam Induced Current (LBIC)



# M&C Core Competency Areas



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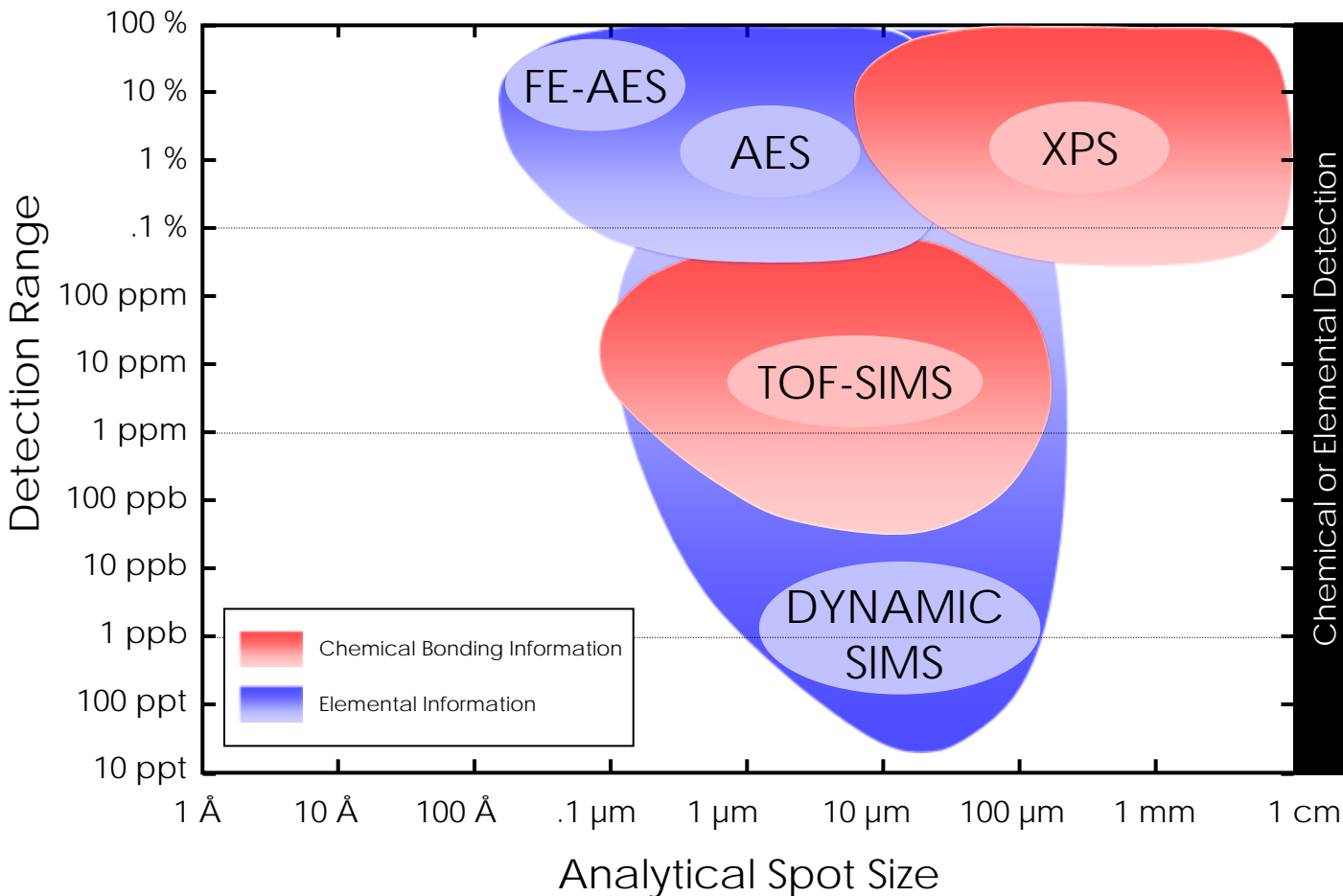
*Sally Asher*  
[sally\\_asher@nrel.gov](mailto:sally_asher@nrel.gov)

# Surface Analysis Team Capabilities



Surface Analysis

## Analytical Resolution versus Sensitivity



### AES

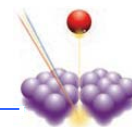
#### Auger Electron Spectroscopy

- Elemental information
- Detects Li - U
- 0-100Å depth resolution
- Depth profiling capable
- Imaging capability

### XPS

#### X-ray Photoelectron Spectroscopy

- Chemical Bonding Info.
- Detects Li - U
- 0-100Å depth resolution
- Depth profiling capable
- Imaging capability



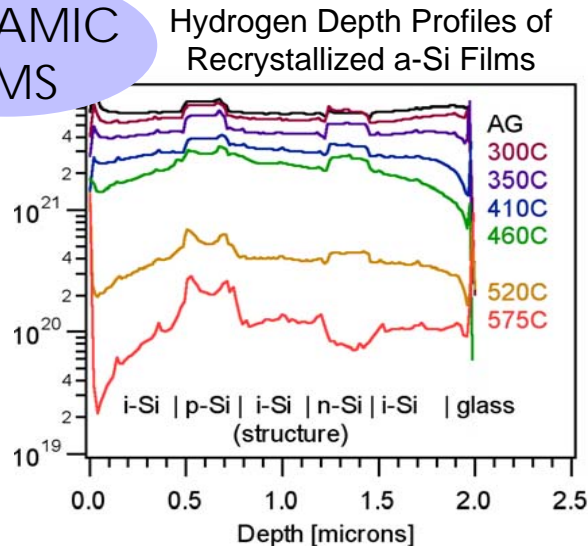
# Secondary Ion Mass Spectrometry (SIMS)

## Time-of-Flight SIMS (TOF-SIMS)



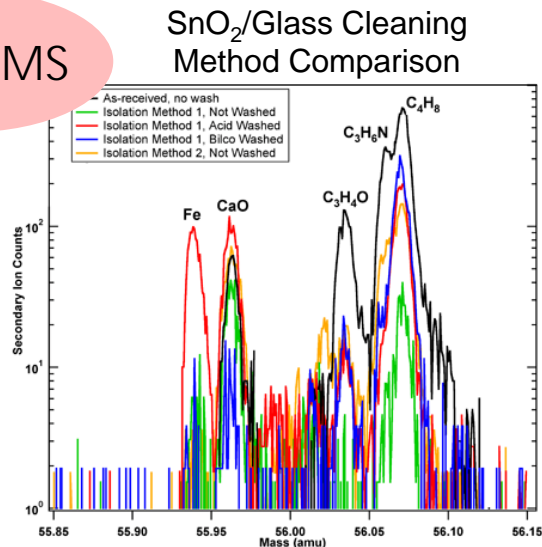
Surface Analysis

### DYNAMIC SIMS



- Extremely sensitive - Detects fractions in the range of parts per million (ppm) to parts per billion (ppb)
- Elemental detection of species ranging from H to U and all isotopes
- Quantitative technique when used with standards
- Depth profiles with resolution of <10 nm - Excellent technique for analyzing interfaces

### TOF-SIMS



- Extremely sensitive - Detects fractions in the parts per million (ppm) range
- Elemental and molecular analysis- good for analyzing organics
- Surface sensitive technique - can study the top few monolayers of material
- Elemental detection of species ranging from H to U and all isotopes
- Depth profiles with resolution of <5 nm

# M&C Core Competency Areas



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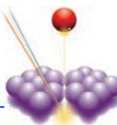
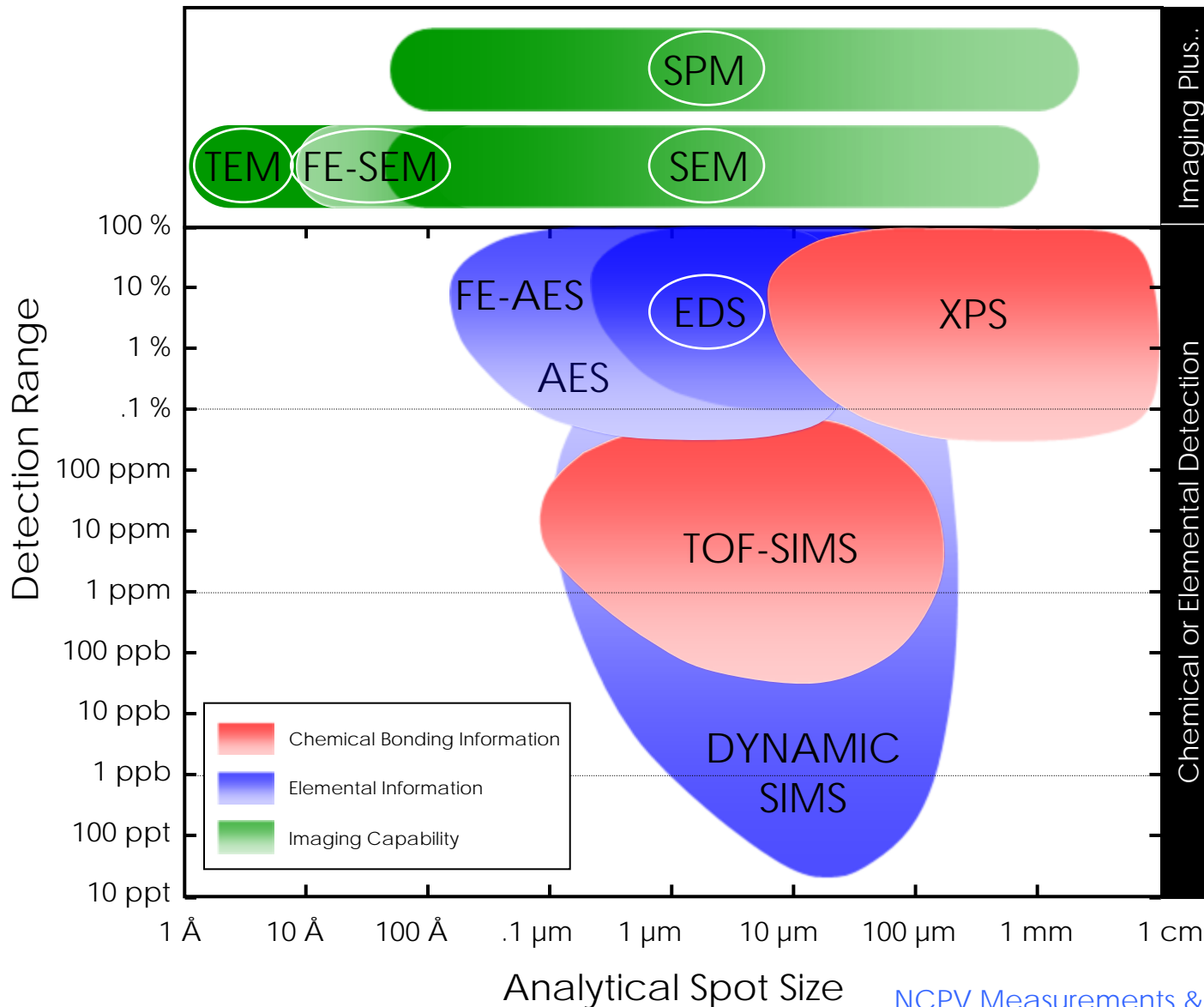


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Microscopy

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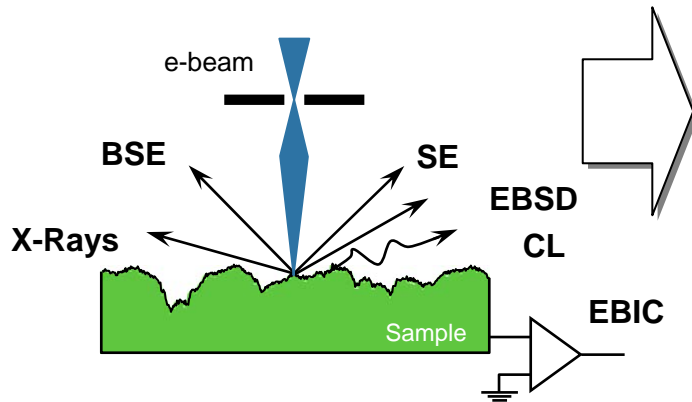
# Analytical Microscopy Team Capabilities



# SEM and SPM Capabilities

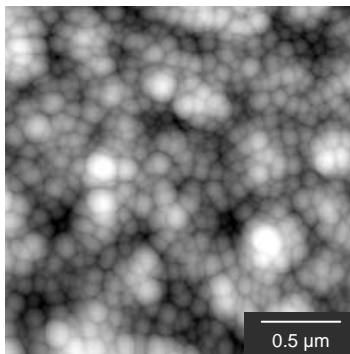


## SEM Operational Modes



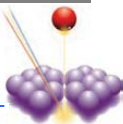
- Secondary Electron (SE) Imaging
- Back Scattered Electron (BSE) Imaging
- Cathodoluminescence (CL)
- Electron beam induced current (EBIC)
- Electron backscattered diffraction (EBSD)
- Energy dispersive x-ray spectroscopy (EDS)

## SPM Operational Modes

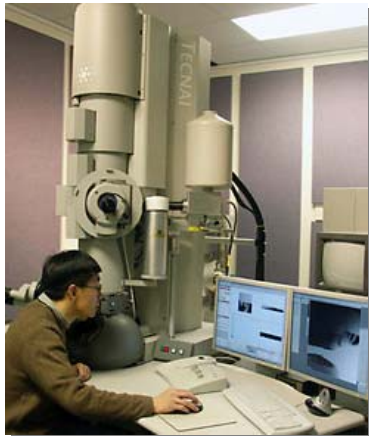


SEM-based

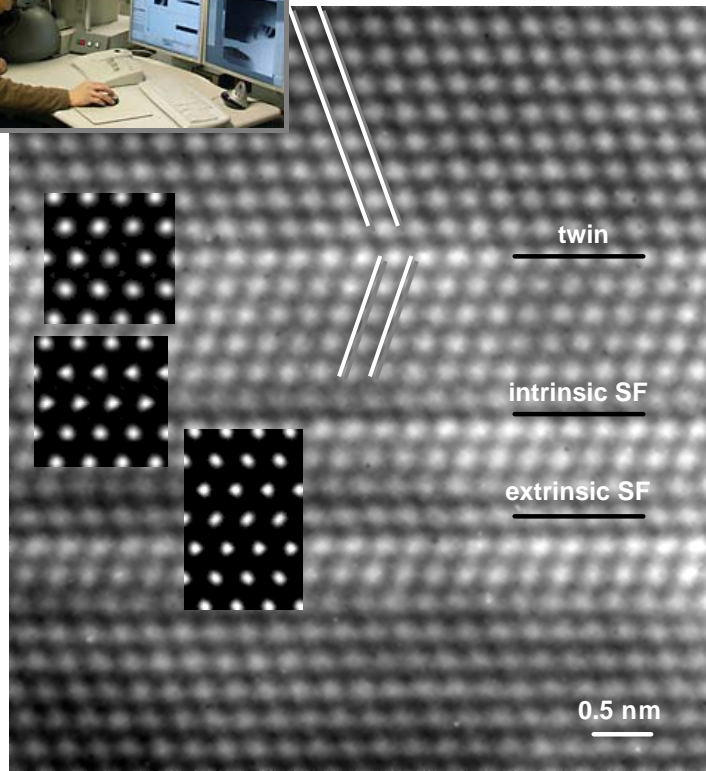
- Atomic Force Microscopy (AFM)
- Conductive AFM (C-AFM)
- Scanning Capacitance Microscopy (SCM)
- Scanning Kelvin Probe Microscopy (SKPM)
- Scanning Tunneling Luminescence (STL)
- Electroluminescence (EL) Mapping
- Near-field cathodoluminescence (NFCL)



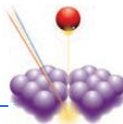
# Transmission Electron Microscopy (TEM)



- **High-Resolution Imaging** - Atomic resolution ( $1.4 \text{ \AA}$ )
- **Structural Analysis** - Electron diffraction and diffraction contrast analysis



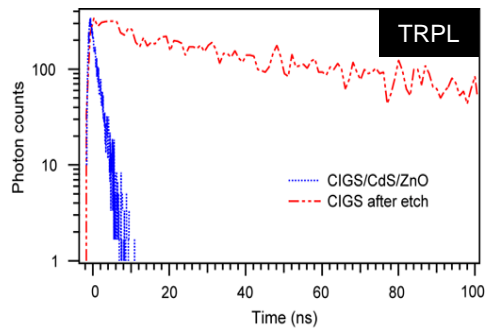
- **Compositional Analysis** - Energy dispersive spectroscopy (B to U,  $\sim 0.5 \text{ at\%}$ )
- **Cross-Sectional Analysis** - New Focused Ion Beam (FIB) capability facilitates cross-sectional sample prep with pin-point accuracy.



# Combining Complementary Techniques



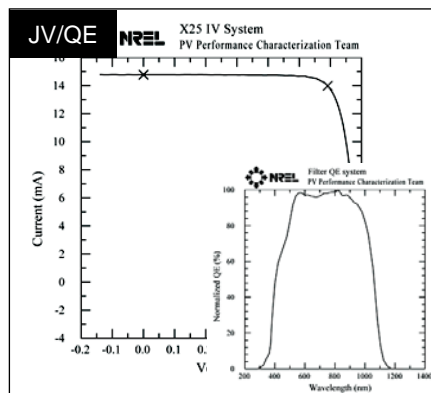
## E-O Characterization



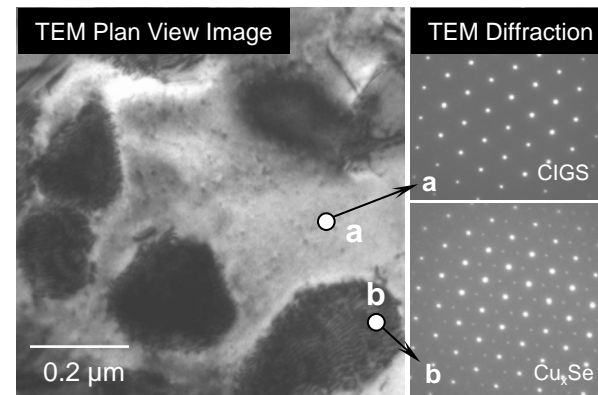
## Process Knowledge



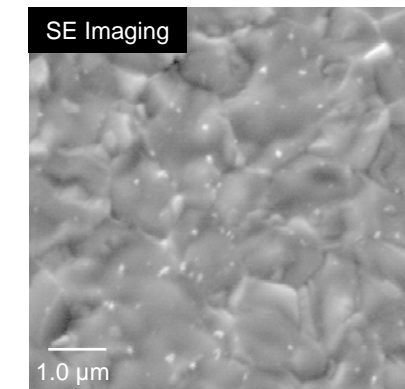
## Device Performance



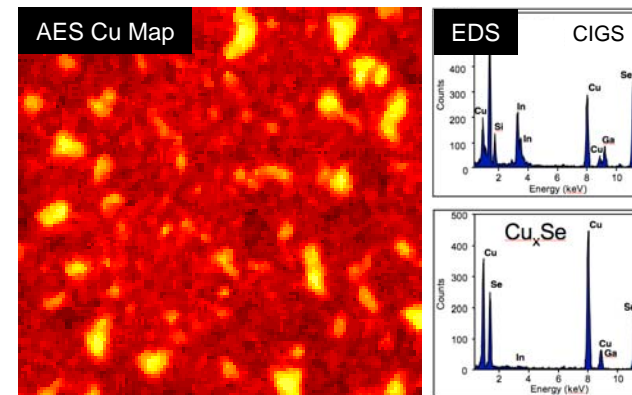
## Structural Characterization



## Topography



## Compositional Characterization



## Device Modeling

